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Mr. Gregory Nichols Naval Research Laboratory 4555 Overlook Ave., S. W. Washington, D. C. 20375-5320

Subject:

CDRL Item 0001, Monthly Progress Report

Reference:

Contract N00014-97-C-2033, "12-Bit High Dynamic Range ADC"

Dear Gregory:

In accordance with the referenced contract, enclosed is the Monthly Progress Report for the period of 15 September 1999 to 15 October 1999.

If I can be of any further assistance, please contact me at (310) 814-5867. Thank you for your consideration.

Sincerely,

Rhona Taylor

Contracts Specialist

Rhone Daylor

Enclosure: as stated

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Monthly Report for

12-Bit High Dynamic Range ADC

Reporting Period: 15 September 1999 to 15 October 1999

NRL Contract No. N00014-97-C-2033

TRW Sales No. 67219

Prepared for:

Gregory M. Nichols

Naval Research Lab

Code: 5725

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Submitted by:

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1.0 Technical Progress

During this reporting period, fabrication of the all-level ADC design iteration continued. In addition, fabrication of the ADC MCM is in progress, and the assembly of the MCM test fixture was initiated.

Figure 1 shows a simplified process flow diagram for the TRW GaAs HBT technology. The first lot of all-level design iteration wafers (6 total) is currently at backside via etch (step 17 of 18). Due to the significant backlog of wafers in the backside processing area, progress of the ADC lot has been very slow. A request for "Hot Lot" status was requested (and granted) to expedite the completion of the ADC lot. The second lot has completed isolation implant (step 6 of 18), and has been placed on hold as a backup.

The ADC MCM fabrication is in progress. MCM delivery is still scheduled for early November, 1999. Figure 2 shows an updated program schedule. The final delivery of MCMs is now projected to be 1/31/2000.

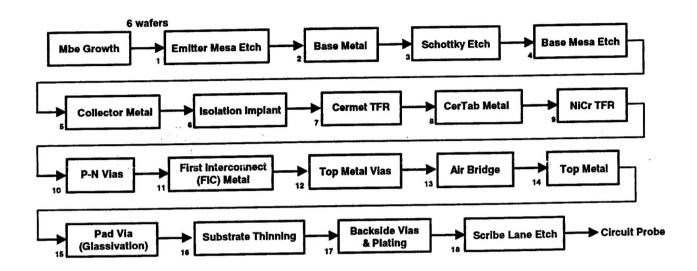


Figure 1. Simplified Process Flow Diagram for TRW's Advanced GaAs HBT Technology.



2. Plans for Next Reporting Period

During the next reporting period, wafer fabrication of the all-level ADC design iteration (first lot) will be completed, and wafer probing initiated. In addition, the ADC MCM fabrication and the MCM test fixture fabrication will both be completed.

3. Financial Status

Table 1 shows the forecasted versus actual expenditures for the Phase 2 program. At month-end September, 1999 the cumulative actuals were \$425.6K versus a forecast of \$540.3K (an underrun of \$115K). However, there are \$49.3K of un-booked commitments associated with MCM material and test fixture purchases. The remaining underrun reflects the MCM schedule slip which has delayed the MCM test activities.

Table 1. Phase 2 Expenditures Forecast

Month	Monthly Total (\$K)	Cumulative Total (\$K)	Cumulative Actuals (\$K)	Delta (Forecast - Actuals)
Mar-99	65.0	65.0	56.9	8.1
Apr-99	109.4	174.4	133.0	41.4
May-99	100.8	275.2	191.2	84.0
Jun-99	107.5	382.7	275.1	107.6
Jul-99	45.9	428.6	356.1	72.5
Aug-99	32.1	460.7	401.5	59.2
Sep-99	79.6	540.3	425.6	114.7
Oct-99	74.6	614.9		
Nov-99	27.0	641.9		
Dec-99	15.1	657.0		

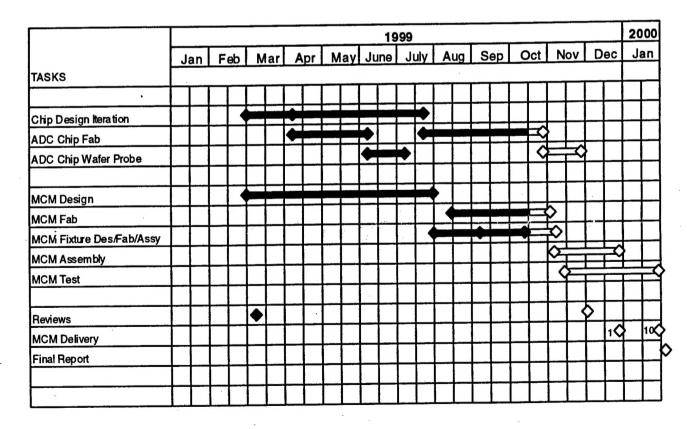


Figure 2. Development Schedule for Phase 2 Activities.

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